



## SOT-23-6 物料成分表

### Material Composition Data

构成部件 Sub-part(if yes)		构成成分 Composition		CAS编号 CAS No.	化学成分%
英文名称 English	重量(mg) Weight	英文名称 English			
Die	1.45	Si		7440-21-3	100.00%
Lead Frame	8.13	Cu		7440-50-8	balance
		Fe		7439-89-6	2.1-2.6%
		P		7723-14-0	0.015-0.15
		Zn		7440-66-6	0.05-0.2
		Pb		7439-92-1	≤0.005
Epoxy	0.12	Silver		7440-22-4	60-100%
		Epoxy Resin.		-	10-30%
		1,4-bis(2,3 epoxypropoxy)butane		2425-79-8	5-10%
		Aromatic polyamine Proprietary		-	1-5%
Wire	0.05	Copper		231-159-6	≥99.99
		Silver		231-131-3	<20ppm
		other		-	-
Mold Compound	5.23	Silicon Dioxide		7631-86-9	60-80%
		Epoxy Cresol Novolac Resin~		29690-82-2	10-20%
		Phenol-formaldehyde polymer		9003-35-4	1- 10 %
		Mg-hydroxide		1309-42-8	1- 10 %
		3-Trimethoxysilylpropane-1-thiol		4420-74-0	0.1- 1 %
		Carbon black		1333-86-4	0.1- 1 %
Plating	0.02	Sn		7440-31-5	99.99%
Total	15				

Notes: Lead in internal soft solder, ROHS exemption clause Annex 7a"lead in high melting temperature type solders" applied. Materials Disclosure Disclaimer: Even though all possible efforts have been made to provide you with the information, it is for guidance only and we cannot guarantee to its accuracy or completeness.